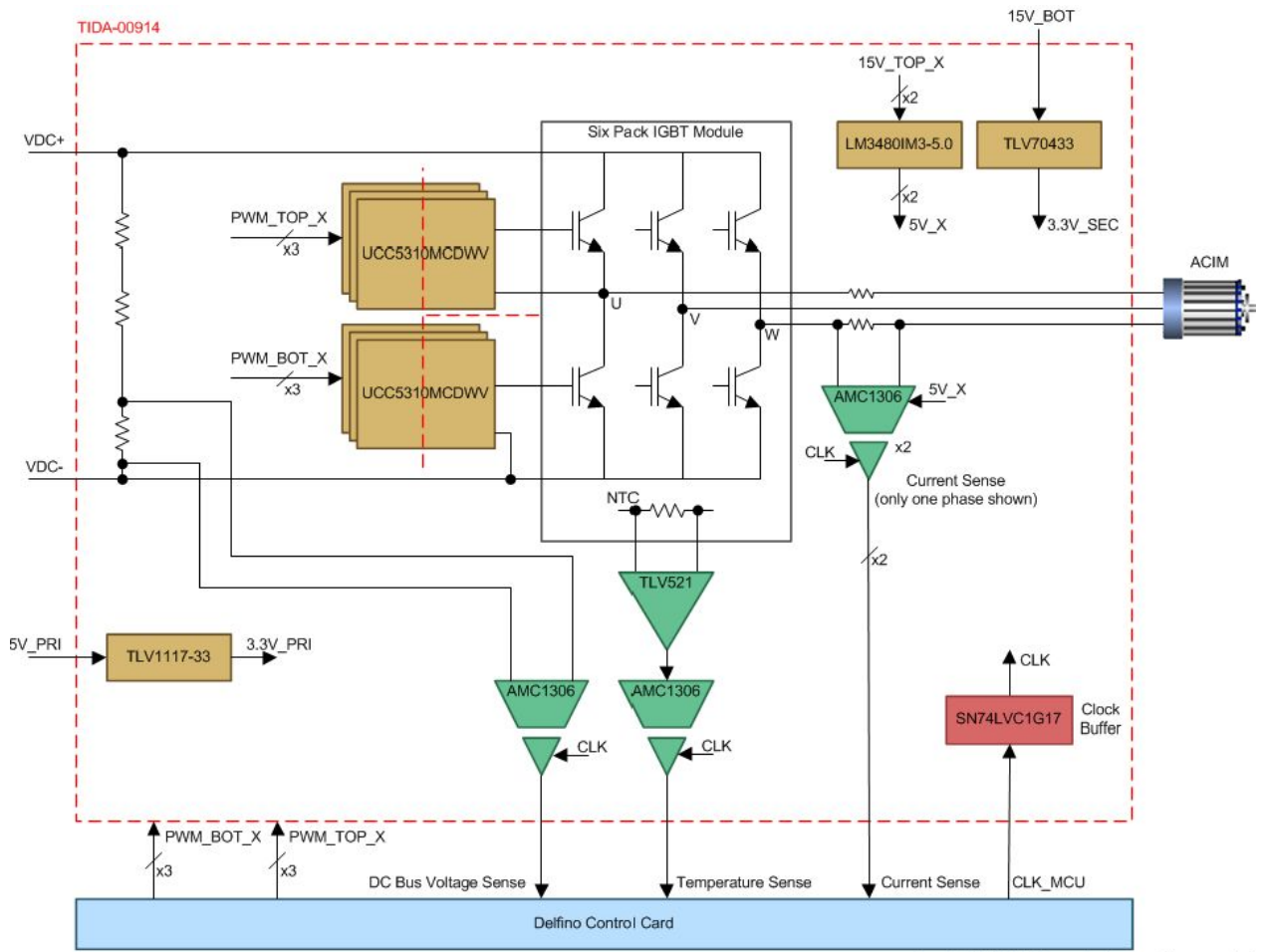


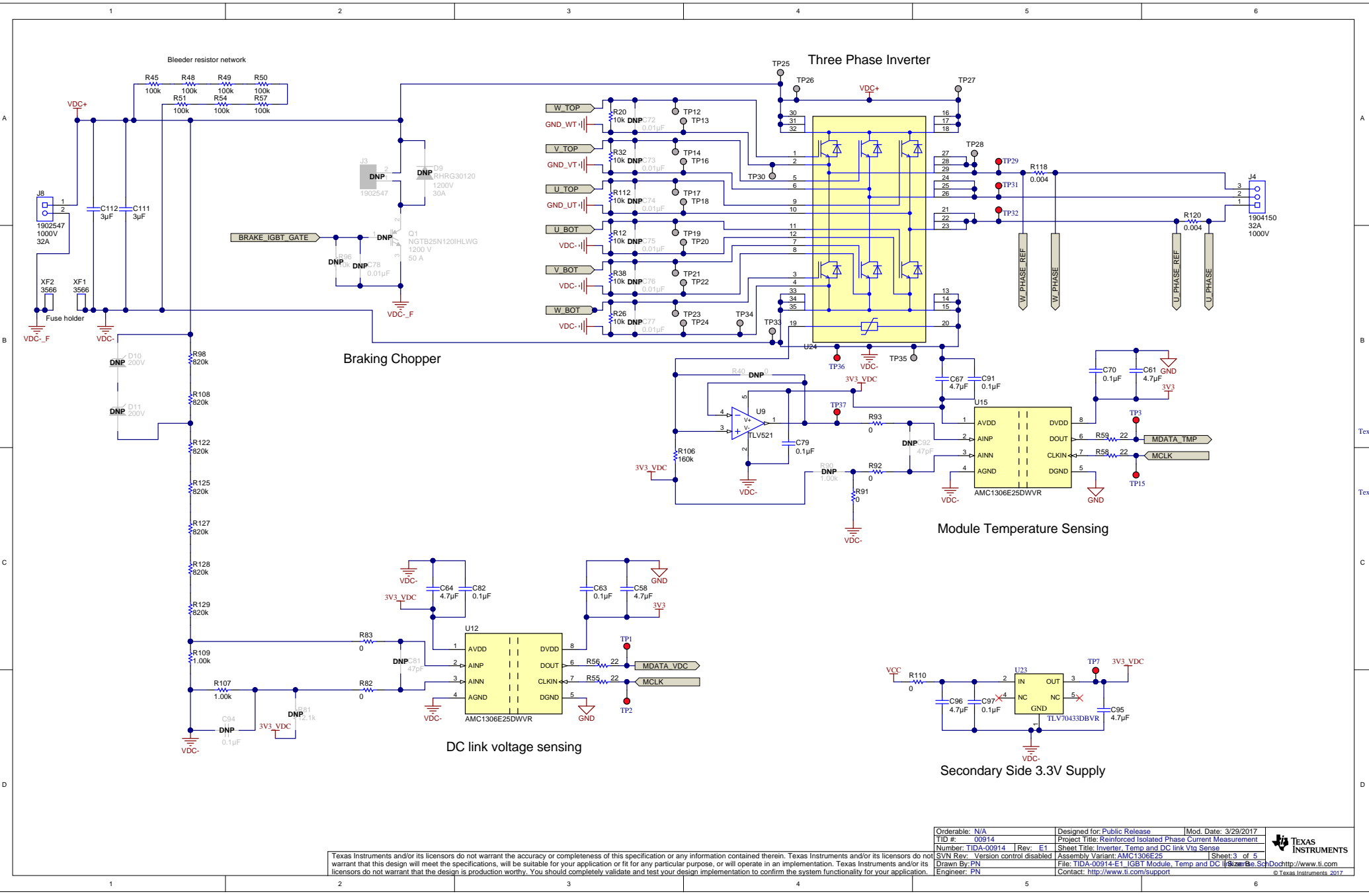
Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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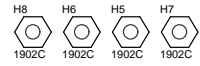
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Orderable: N/A	Designed for: Public Release	Mod. Date: 4/4/2018	 http://www.ti.com
TID #: 00914	Project Title: Reinforced Isolated Phase Current Measurement		
Number: TIDA-00914 Rev: E1	Sheet Title: Block Diagram		
SVN Rev: Version control disabled	Assembly Variant: AMC1306E25	Sheet: 1 of 5	
Drawn By: PN	File: TIDA-00914-E1_CoverSheet_SchDoc	Size: B	
Engineer: PN	Contact: http://www.ti.com/support		



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TID #: 00914	Project Title: Reinforced Isolated Phase Current Measurement	
Number: TIDA-00914 Rev: E1	Sheet Title: Inverter_Temp and DC link Vlg Sense	
SVN Rev: Version control disabled	Assembly Variant: AMC1306E25	Sheet: 3 of 5
Drawn By: PN	File: TIDA-00914-E1_IGBT_Module_Temp and DC link Vlg Sense	Size: Be.SchDoc.tpt / www.ti.com
Engineer: PN	Contact: http://www.ti.com/support	© Texas Instruments 2017



PCB Number: TIDA-00914
PCB Rev: E1

LBL1
PCB Label
Size: 0.65" x 0.20"

PCB LOGO
Pb-Free Symbol
PCB LOGO
FCC disclaimer
PCB LOGO
ESD Sensitive



ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Variant/Label Table	
Variant	Label Text
001	AMC1306E25

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Orderable: N/A	Designed for: Public Release	Mod. Date: 3/29/2017
TID #: 00914	Project Title: Reinforced Isolated Phase Current Measurement	
Number: TIDA-00914 Rev: E1	Sheet Title: Hardware	
SVN Rev. Version control disabled	Assembly Variant: AMC1306E25	Sheet: 5 of 5
Drawn By: PN	File: TIDA-00914-E1_EVM_Hardware.SchDoc	Size: B
Engineer: PN	Contact: http://www.ti.com/support	



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